

**IN THE DESCRIPTION**

Please rewrite the paragraph starting at Page 12, Line 5 to read as follows:

As shown in Fig. 8, the first gold bump 13 is formed on the glass 45 18 so as to be electrically connected to the pattern 110 of the CMOS image sensor chip.

Please rewrite the paragraph starting at Page 12, Line 21 to read as follows:

As shown in Fig. 13, the circuit 44 15 is bonded with the second gold bump 14 by means of ultrasonic wave and heat so as to be electrically connected to each other.

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